



**NOMINAL SIZE =** 0.75 in x 0.5 in  
(19,05 mm x 12,7 mm)

### Features

- Up to 6-A Output Current
- 12-V Input Voltage
- Wide-Output Voltage Adjust (1.2 V to 5.5 V)
- Efficiencies up to 92 %
- 230 W/in<sup>3</sup> Power Density
- On/Off Inhibit
- Under-Voltage Lockout
- Output Over-Current Protection (Non-Latching, Auto-Reset)
- Surface Mountable
- Operating Temp: -40 to +85 °C
- DSP Compatible Output Voltages
- IPC Lead Free 2

### Description

The PTH12000 series of non-isolated power modules are small in size and high on performance. Using double-sided surface mount construction and synchronous rectification technology, these regulators deliver up to 6 A of output current while occupying a PCB area of about half the size of a standard postage stamp. They are an ideal choice for applications where space, performance and cost are important design constraints.

The series operates from an input voltage of 12 V to provide step-down power conversion to any output voltage over the range, 1.2 V to 5.5 V. The output voltage of the PTH12000W is set within this range using a single resistor.

Operating features include an on/off inhibit, output voltage adjust (trim), and output over-current protection.

Target applications include telecom, industrial, and general purpose circuits, including low-power dual-voltage systems that use a DSP, microprocessor, or ASIC.

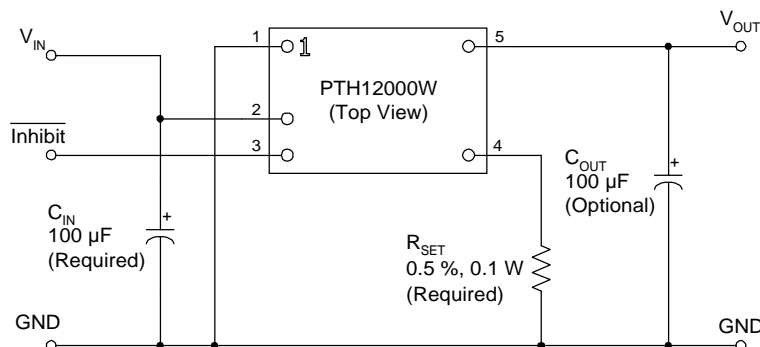
Package options include both through-hole and surface mount configurations.

### Pin Configuration

Pin	Function
1	GND
2	V <sub>in</sub>
3	Inhibit *
4	V <sub>o</sub> Adjust
5	V <sub>out</sub>

\* Denotes negative logic:  
Open = Output On  
Ground = Output Off

### Standard Application



R<sub>set</sub> = Resistor to set the desired output voltage (see spec. table for values)  
C<sub>in</sub> = Required electrolytic 100 μF  
C<sub>out</sub> = Recommended 100 μF electrolytic

### Ordering Information

Output Voltage (PTH12000□xx)		Package Options (PTH12000x□□) <sup>(1)</sup>		
Code	Voltage	Code	Description	Pkg Ref. <sup>(2)</sup>
W	1.2 V – 5.5 V (Adjust)	AH	Horiz. T/H	(EUS)
		AS	SMD, Standard <sup>(3)</sup>	(EUT)

**Notes:** (1) Add “T” to end of part number for tape and reel on SMD packages only.  
(2) Reference the applicable package reference drawing for the dimensions and PC board layout  
(3) “Standard” option specifies 63/37, Sn/Pb pin solder material.

### Pin Descriptions

**Vin:** The positive input voltage power node to the module, which is referenced to common GND.

**GND:** This is the common ground connection for the ‘Vin’ and ‘Vout’ power connections. It is also the 0 VDC reference for the ‘Inhibit’ and ‘Vo Adjust’ control inputs.

**Vout:** The regulated positive power output with respect to the GND node.

**Inhibit:** The Inhibit pin is an open-collector/drain negative logic input that is referenced to GND. Applying a low-level ground signal to this input disables the module’s output and turns off the output voltage. When the Inhibit control is active, the input current drawn by the regulator is significantly reduced. If the Inhibit pin is left open-circuit, the module will produce an output whenever a valid input source is applied.

**Vo Adjust:** A 0.5 %, 0.1 W resistor must be connected between this pin and the GND pin to set the output voltage to the desired value. The set point range for the output voltage is from 1.2 V to 5.5 V. The resistor required for a given output voltage may be calculated from the following formula. If left open circuit, the module output will default to its lowest output voltage value. For further information on the adjustment and/or trimming of the output voltage, consult the related application note.

$$R_{\text{set}} = 10 \text{ k} \cdot \frac{0.8 \text{ V}}{V_{\text{out}} - 1.2 \text{ V}} - 1.82 \text{ k}$$

The specification table gives the preferred resistor values for a number of standard output voltages.

**Environmental & Absolute Maximum Ratings** (Voltages are with respect to GND)

Characteristics	Symbols	Conditions	Min	Typ	Max	Units
Operating Temperature Range	$T_a$	Over $V_{in}$ Range	-40 <sup>(i)</sup>	—	+85	°C
Solder Reflow Temperature	$T_{reflow}$	Surface temperature of module body or pins	—	—	215 <sup>(ii)</sup>	°C
Storage Temperature	$T_s$	—	-40	—	+125	°C
Mechanical Shock	—	Per Mil-STD-883D, Method 2002.3 1 msec, ½ sine, mounted	—	TBD	—	G's
Mechanical Vibration	—	Mil-STD-883D, Method 2007.2 20-2000 Hz	—	TBD	—	G's
Weight	—	—	—	2	—	grams
Flammability	—	Meets UL 94V-O	—	—	—	—

**Notes:** (i) For operation below 0 °C the external capacitors must have stable characteristics. Use either a low ESR tantalum or Oscon® capacitor.  
(ii) During reflow of SMD package version do not elevate peak temperature of the module, pins or internal components above the stated maximum. For further guidance refer to the application note, "Reflow Soldering Requirements for Plug-in Power Surface Mount Products."

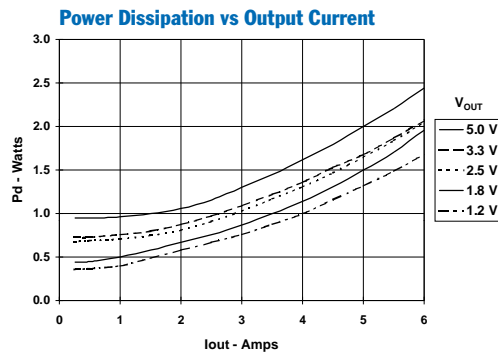
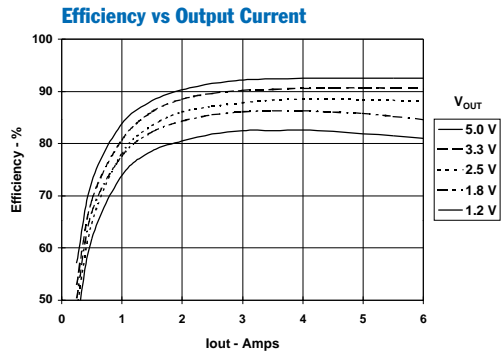
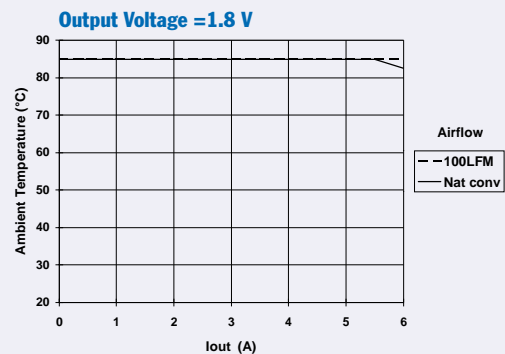
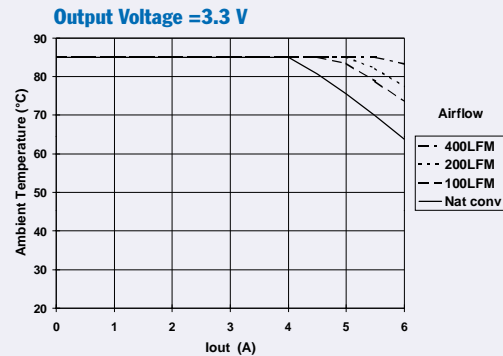
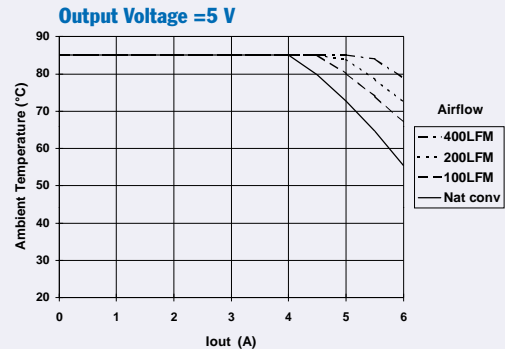
**Electrical Specifications** Unless otherwise stated,  $T_a = 25$  °C,  $V_{in} = 12$  V,  $V_{out} = 3.3$  V,  $C_{in} = 100$   $\mu$ F,  $C_{out} = 0$   $\mu$ F, and  $I_o = I_o$  max

Characteristics	Symbols	Conditions	PTH12000W			Units
			Min	Typ	Max	
Output Current	$I_o$	$T_a = 60$ °C, 200 LFM $T_a = 25$ °C, natural convection	0 0	— —	6 <sup>(1)</sup> 6 <sup>(1)</sup>	A
Input Voltage Range	$V_{in}$	Over $I_o$ range	10.8	—	13.2	V
Set-Point Voltage Tolerance	$V_o$ tol	—	—	—	±2	% $V_o$
Temperature Variation	$\Delta Reg_{temp}$	-40 °C < $T_a$ < +85 °C	—	±0.5	—	% $V_o$
Line Regulation	$\Delta Reg_{line}$	Over $V_{in}$ range	—	±5	—	mV
Load Regulation	$\Delta Reg_{load}$	Over $I_o$ range	—	±5	—	mV
Total Output Variation	$\Delta Reg_{tot}$	Includes set-point, line, load, -40 °C ≤ $T_a$ ≤ +85 °C	—	—	±3	% $V_o$
Efficiency	$\eta$	$V_{in} = 12$ V, $I_o = 4$ A RSET = 280 $\Omega$ $V_o = 5.0$ V RSET = 2.0 k $\Omega$ $V_o = 3.3$ V RSET = 4.32 k $\Omega$ $V_o = 2.5$ V RSET = 8.06 k $\Omega$ $V_o = 2.0$ V RSET = 11.5 k $\Omega$ $V_o = 1.8$ V RSET = 24.3 k $\Omega$ $V_o = 1.5$ V RSET = open cct $V_o = 1.2$ V	— — — — — — —	92 90 88 87 86 84 82	— — — — — — —	%
$V_o$ Ripple (pk-pk)	$V_r$	20 MHz bandwidth, $I_o = 4$ A $V_o \geq 3.3$ V $V_o \leq 2.5$ V	— —	50 30	— —	mVpp
Transient Response	$t_{tr}$ $\Delta V_{tr}$	1 A/ $\mu$ s load step, 50 to 100 % $I_o$ max, $V_o = 1.8$ V, $C_{out} = 100$ $\mu$ F Recovery time $V_o$ over/undershoot	— —	70 100	— —	$\mu$ Sec mV
Over-Current Threshold	$I_o$ trip	Reset followed by auto-recovery	—	12	—	A
Under-Voltage Lockout	UVLO	$V_{in}$ increasing $V_{in}$ decreasing	— 8.8	— —	10.4 —	V
Inhibit Control (pin 3) Input High Voltage Input Low Voltage Input Low Current	$V_{IH}$ $V_{IL}$ $I_{IL}$	Referenced to GND Pin 3 to GND	$V_{in} - 0.5$ -0.2	— —	Open <sup>(2)</sup> 0.5	V
Standby Input Current	$I_{in}$ standby	pins 1 & 3 connected	—	1	—	mA
Switching Frequency	$f_s$	Over $V_{in}$ and $I_o$ ranges	—	350	—	kHz
External Input Capacitance	$C_{in}$	—	100 <sup>(3)</sup>	—	—	$\mu$ F
External Output Capacitance	$C_{out}$	—	0	100 <sup>(4)</sup>	TBD	$\mu$ F
Reliability	MTBF	Per Bellcore TR-332 50 % stress, $T_a = 40$ °C, ground benign	10	—	—	10 <sup>6</sup> Hrs

**Notes:** (1) See SOA curves or consult factory for appropriate derating.  
(2) The Inhibit control (pin 3) has an internal pull-up to  $V_{in}$ , and if left open-circuit the module will operate when input power is applied. A small low-leakage (<100 nA) MOSFET is recommended to control this input. See application notes for more information.  
(3) The regulator requires a minimum of 100  $\mu$ F input capacitor with a minimum 750 mArms ripple current rating. For further information, consult the related application note on Capacitor Recommendations.  
(4) An external output capacitor is not required for basic operation. Adding 100  $\mu$ F of distributed capacitance at the load will improve the transient response.

6-A, 12-V Input Non-Isolated  
Wide-Output Adjust Power Module

SLTS202A – MAY 2003 – REVISED MAY 2003

Characteristic Data;  $V_{in} = 12\text{ V}$  (See Note A)Safe Operating Area;  $V_{in} = 12\text{ V}$  (See Note B)

ADVANCE INFORMATION

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**Note A:** Characteristic data has been developed from actual products tested at  $25^{\circ}\text{C}$ . This data is considered typical data for the Converter.

**Note B:** SOA curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 4 in.  $\times$  4 in. double-sided PCB with 1 oz. copper.

## Capacitor Recommendations for the PTH12000 6-A Kestrel Regulator Series

### Input Capacitors

The recommended input capacitance is determined by 750 mA (rms) minimum ripple current rating, less than 150 mΩ equivalent series resistance (ESR) and 100 µF minimum capacitance. The ripple current rating, ESR, and operating temperature are the major considerations when selecting the input capacitor.

It is recommended that tantalum capacitors have a minimum voltage rating of at least twice the working voltage, including the ac ripple. This is necessary to insure reliability with 12-V input voltage bus applications. Only one tantalum capacitor (68 µF, 25 V) was found to meet this requirement.

### Output Capacitors (Optional)

The ESR of the required capacitor can be less than, or equal to 150 mΩ. Electrolytic capacitors have poor ripple performance at frequencies greater than 400 kHz but excellent low frequency transient response. Above the ripple frequency, ceramic decoupling capacitors are necessary to improve the transient response and reduce any high frequency noise components apparent during higher current excursions. Preferred low ESR type capacitor's part numbers are identified in the capacitor table.

### Tantalum/ Ceramic Capacitors

Tantalum capacitors are acceptable on the output bus. Either tantalum or Os-con® capacitor types are recommended for applications where ambient temperatures fall below 0 °C. Electrolytic capacitors may be substituted with ceramic types with the minimum capacitance on the input bus.

### Capacitor Table

Table 2-1 identifies capacitors with acceptable ESR and maximum allowable ripple current (rms) ratings. Capacitors recommended for the output are identified under the Output Bus column with the required quantity.

*This is not an extensive capacitor list. Capacitors from other vendors are available with comparable specifications. Those listed are for guidance. The RMS ripple current rating and ESR (at 100 kHz) are critical parameters necessary to insure both optimum regulator performance and long capacitor life.*

**Table 2-1 Recommended Input/Output Capacitors**

Capacitor Vendor/ Component Series	Capacitor Characteristics					Quantity		Vendor Number
	Working Voltage	Value (µF)	(ESR) Equivalent Series Resistance	85 °C Maximum Ripple Current (Irms)	Physical Size (mm)	Input Bus	Output Bus	
Panasonic FC	25 V 35 V 35 V	330 µF 180 µF 220 µF	0.090 Ω 0.090 Ω 0.090 Ω	755 mA 755 mA 755 mA	10×12.5 10×12.5 10×12.5	1 1 1	1 1 1	EEUFC1E331 EEUFC1V181 EEUFC1V221
United Chemi-con PXA FP FS LXZ	16 V 20 V 20 V 35 V	150 µF 120 µF 100 µF 220 µF	0.026 Ω 0.024 Ω 0.030 Ω 0.090 Ω	3430 mA 3100 mA 2740 mA 760 mA	10×7.7 8×10.5 8×10.5 10×12.5	1 1 1 1	1 1 1 1	PXA16VC151MJ80TP 20FP120MG 20FS100M LXZ35VB221M10X12LL
Nichicon NX (Surface Mt) NA PM	16 V 20 V 35 V	150 µF 100 µF 220 µF	0.026 Ω 0.025 Ω 0.090 Ω	3450 mA 3700 mA 770 mA	10×8 10×10 10×15	1 1 1	1 1 1	PNX1C151MCR1GS PNA1D101M1 UPM1V221MHH6
Panasonic FK (Surface Mt)	25 V 35 V	470 µF 330 µF	0.080 Ω 0.080 Ω	850 mA 850 mA	10×10.2 10×10.2	1 1	1 1	EEVFK1E471P EEVFK1V331P
Os-con SVP (Surface Mt) SP SS	20 V 20 V 20 V	100 µF 120 µF 100 µF	0.024 Ω 0.024 Ω 0.030 Ω	>3300 mA >3100 mA >2700 mA	8×12 8×10.5 8×10.5	1 1 1	1 1 1	20SVP100M 20SP120M 20SS100M
AVX Tantalum TPS	10 V 10 V 25 V	100 µF 220 µF 68 µF	0.100 Ω 0.100 Ω 0.095±2 Ω	>1090 mA >1414 mA >1451 mA	7.3L ×4.3W ×4.1H	N/R N/R 2	1 1 1	TPSD107M010R0100 TPSV227M010R0100 TPSV686M025R0095
Kemet T520/T495	10 V 10 V	100 µF 100 µF	0.080 Ω 0.100 Ω	1200 mA >1100 mA	7.3L×5.7W ×4.0H	N/R N/R	1 1	T520D107M010AS T495X107M010AS
Sprague 594D	10 V 25 V	150 µF 68 µF	0.090 Ω 0.095 Ω	1100 mA 1600 mA	7.3L ×6.0W ×4.1H	N/R 2	1 1	594D157X0010C2T 594D686X0025R2T

N/R Not recommended. The voltage rating does not meet the minimum operating limits.

DOUBLE SIDED MODULE

The image contains three mechanical drawings of a PCB layout:

- TOP VIEW:** A rectangular layout with dimensions 0.745 (18,92) and 0.625 (15,88) for the top section, and 0.060 (1,52) for the left margin. Vertical dimensions include 0.250 (6,35), 0.125 (3,18), 0.375 (9,52), and 0.495 (12,57). Five circular features are numbered 1 through 5.
- SIDE VIEW:** A cross-sectional view showing the assembly on a "Host Board". It indicates a "Lowest Component" with a "0.010 MIN. (0,25) Bottom side Clearance". A dimension of 0.140 (3,55) is shown for the top section, and 0.335 (8,50) MAX. for the bottom section. A note specifies "Ø0.040 (1,02) 5 Places Note F, G."
- PC LAYOUT:** A detailed layout showing dimensions 0.785 (19,94) and 0.625 (15,88) for the top section, and 0.080 (2,03) for the left margin. Vertical dimensions include 0.250 (6,35), 0.125 (3,18), 0.375 (9,52), and 0.535 (13,59). Five circular features are numbered 1 through 5. A note "Note E" points to a dashed line, and another note specifies "Ø0.055 (1,40) Min. 5 Places Plated through holes."

F. Pins are 0.040" (1.02) diameter with  
0.070" (1.78) diameter standoff shoulder.

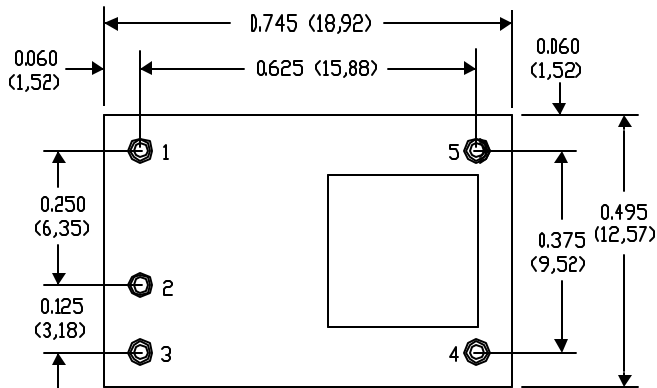
G. All pins: Material - Copper Alloy  
Finish - Tin (100%) over Nickel plate

SCALE	SIZE	REV	SHEET
3X			2 / 3

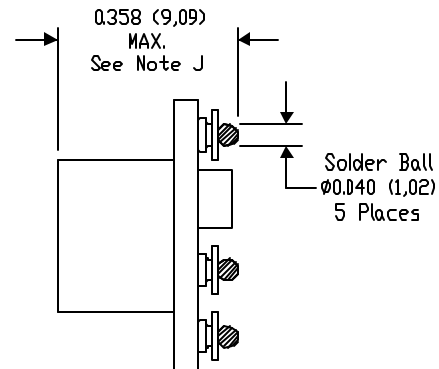
EUT (R-PDSS-B5)

DOUBLE SIDED MODULE

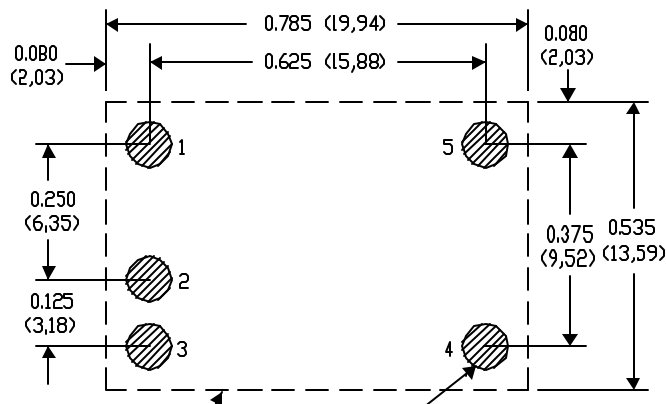
Suffix S



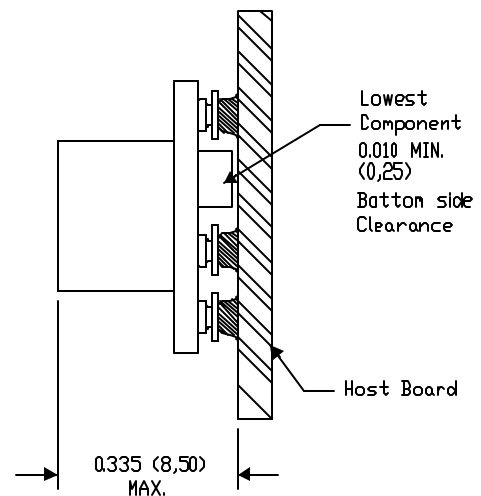
TOP VIEW



SIDE VIEW



PC LAYOUT



/A 3/03

- NOTES:
- A. All linear dimensions are in inches (mm).
  - B. This drawing is subject to change without notice.
  - C. 2 place decimals are  $\pm 0.030$  ( $\pm 0,76$ mm).
  - D. 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
  - E. Recommended keep out area for user components.
  - F. Power pin connection should utilize two or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
  - G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).
  - H. Pad type: Solder mask defined.
  - I. All pins: Material - Copper Alloy  
Finish - Th (100%) over Nickel plate  
Solder Ball - See product data sheet.
  - J. Dimension prior to reflow solder.

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